

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HEE JU SEO	04/10/2019
JAE WON CHOI	04/10/2019
SUNG BOK HONG	04/10/2019
YOUNG JIN HWANG	04/10/2019
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16401558
CORRESPONDENCE DATA	
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SIGNATURE:	/Bradley Edelman/
DATE SIGNED:	05/03/2019
Total Attachments: 4	
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**COMBINED DECLARATION (37 CFR §1.63) FOR UTILITY PATENT APPLICATION AND
ASSIGNMENT FORM¹ FOR MORE THAN ONE ASSIGNEE**

The undersigned acknowledge that this document is being used both as an assignment of the invention and as the declaration (37 CFR 1.63) for a Utility or Design Application.

WHEREAS, the undersigned inventors have invented:

Title: **SEMICONDUCTOR PACKAGE MOLDING DEVICE AND METHOD OF
MANUFACTURING SEMICONDUCTOR DEVICE**

for which Inventors are about to make or have made United States or International application for patent.

WHEREAS, as a below named inventor(s), I/(we) hereby declare that:

Section I. Declaration

This declaration is directed to:

- ☒ The attached U.S. non-provisional patent application, or
- ☐ U.S. non-provisional patent application number _____, filed on _____, or
- ☐ PCT international patent application number _____, filed on _____.

The above-identified application was made or authorized to be made by me (us).

I (we) believe that I am (we are) the original inventor (original joint inventors) of a claimed invention in the above-identified application.

I (we) hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

¹ This form requires the use of an Application Data Sheet.

SEC Ref No. **II-201805-004-1-US0**

Attorney Ref No. **SAM-56233**

I (we) hereby state that I (we) have reviewed and understand the contents of the above identified application, including the claims.

I (we) acknowledge that I am (we are) aware of the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56.

Section II. Assignment

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned, the undersigned hereby sell(s) and assign(s) to

Samsung Electronics Co., Ltd.

having an address at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do 16677, Republic of Korea (hereinafter designated as the Assignee), the entire (100%) right, title and interest for the United States as defined in 35 USC §100, in the invention described in the application identified in Section I of this document.

Assignor hereby confirms any prior assignment to Assignee, and to the extent that Assignor has not already done so, agrees to assign, and hereby does, sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America and throughout the world, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the inventions as described in the aforesaid application, to the aforesaid application itself, and all divisions, continuations, continuations-in-part, or other applications claiming priority directly or indirectly from the aforesaid application, and any United States or foreign Letters Patent, utility model, or other similar rights which may be granted thereon, including reissues, reexaminations and extensions thereof, and all copyright rights throughout the world in the aforesaid application and the subject matter disclosed therein, these rights, title and interest to be held and enjoyed by Assignee to the full end of the term for which the Letters Patent, utility model, or other similar rights, are granted and any extensions thereof as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made, and the right to sue for, and recover for past infringements of, or liabilities for, any of the rights relating to any of the applications, patents, utility models, or other similar rights, resulting therefrom, and the copyright rights;

Assignor hereby covenants and agrees to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights, and for copyright, in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-

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examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

Assignor hereby covenants that no assignment, sale, license, agreement or encumbrance has been or will be entered into which would conflict with this Assignment; and

Assignor hereby requests the United States Patent and Trademark Office to issue the Letters Patent of the United States of America to Assignee, and requests that any official of any country or countries foreign to the United States, whose duty it is to issue or grant patents and applications as aforesaid, to issue the Letters Patent, Utility Model Registration or other similar right to Assignee.

The undersigned hereby grant(s) the law firm of **Muir Patent Law, PLLC** the power to insert on this Declaration and Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

Section III. Inventor(s)/Assignor(s) Signature(s)

LEGAL NAME OF FIRST INVENTOR/ASSIGNOR	Family Name 설비혁신그룹(TSP총괄)/서희주/90708604	First Given Name Hee Ju	Second Given Name
SIGNATURE  DATE 2019-04-10			

SEC Ref No. II-201805-004-1-US0

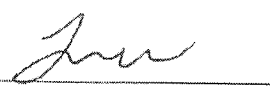
Attorney Ref No. SAM-56233

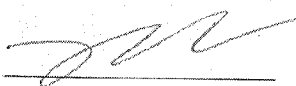
COMBINED DECLARATION (37 CFR 1.63) FOR UTILITY PATENT APPLICATION AND ASSIGNMENT FORM

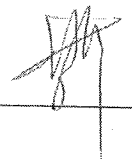
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PATENT
REEL: 049077 FRAME: 0755

LEGAL NAME OF SECOND INVENTOR/ASSIGNOR	Family Name	First Given Name	Second Given Name
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SIGNATURE  DATE <u>2019. 04. 10</u>			

LEGAL NAME OF THIRD INVENTOR/ASSIGNOR	Family Name	First Given Name	Second Given Name
	HONG	Sung Bok	
SIGNATURE  DATE <u>2019. 04. 10</u> 설비혁신그룹(TSP총괄)/서희주/90708604			

LEGAL NAME OF FOURTH INVENTOR/ASSIGNOR	Family Name	First Given Name	Second Given Name
	HWANG	Young Jin	
SIGNATURE  DATE <u>2019. 04. 10.</u>			

SEC Ref No. II-201805-004-1-US0Attorney Ref No. SAM-56233

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RECORDED: 05/03/2019

PATENT
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